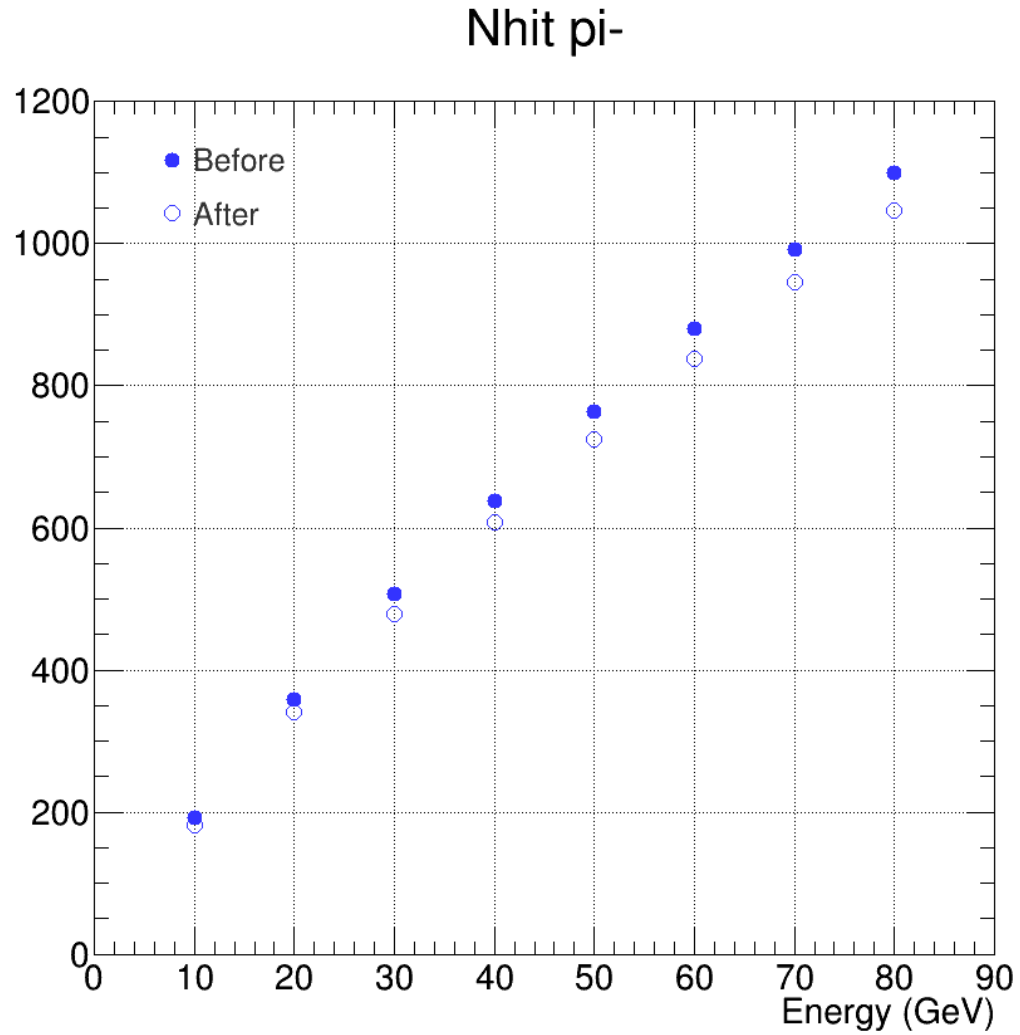


SDHCAL Simulation Status

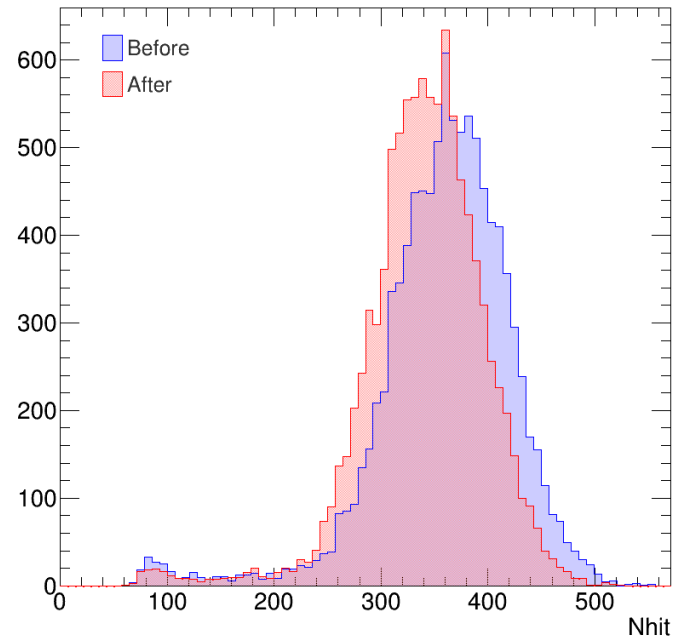
Simulation

- Changes in simulation :
 - PCB : changed from vacuum to g10
 - Electronics mask : changed from vacuum to epoxy
 - Absorber : changed from 7.85 g/cm³ steel to 8 g/cm³ steel to match 304L / 316L steel specifications
 - A 1mm air layer has been added between the structure 15mm steel layers and the cassette 2.5 mm steel layers (that was previously single 20mm steel layers)

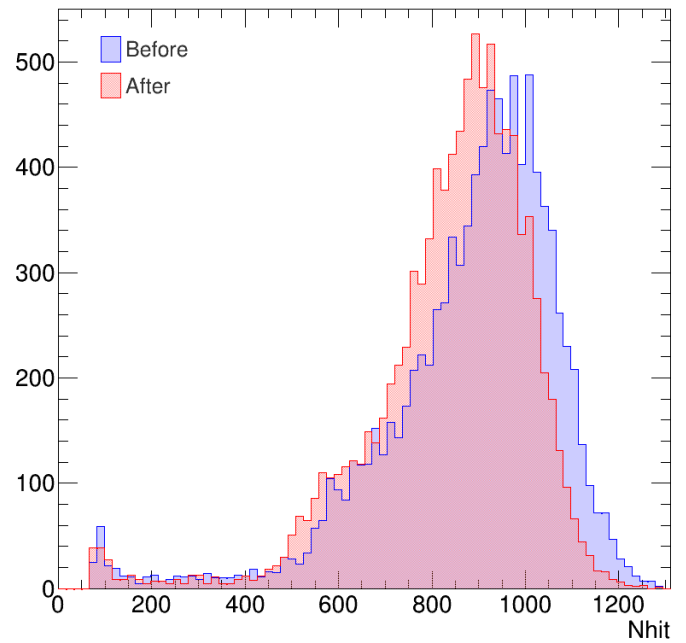
Simulation



20 pi- , FTF_BIC

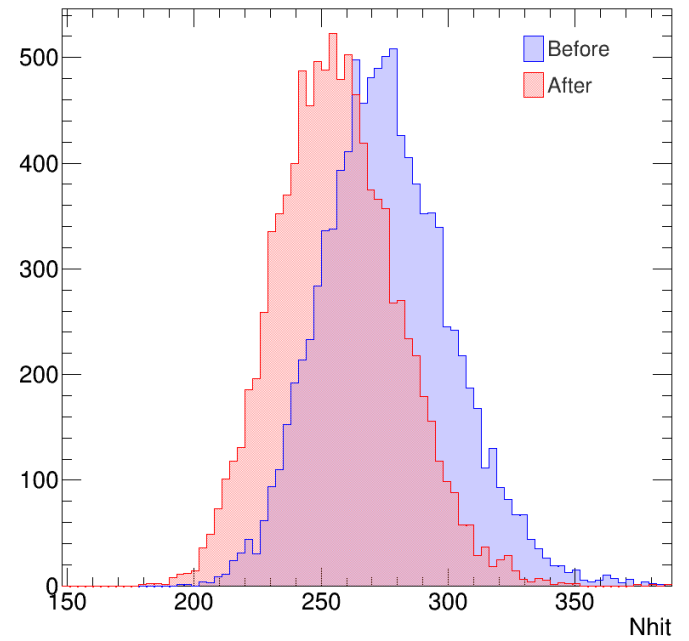


60 pi- , FTF_BIC

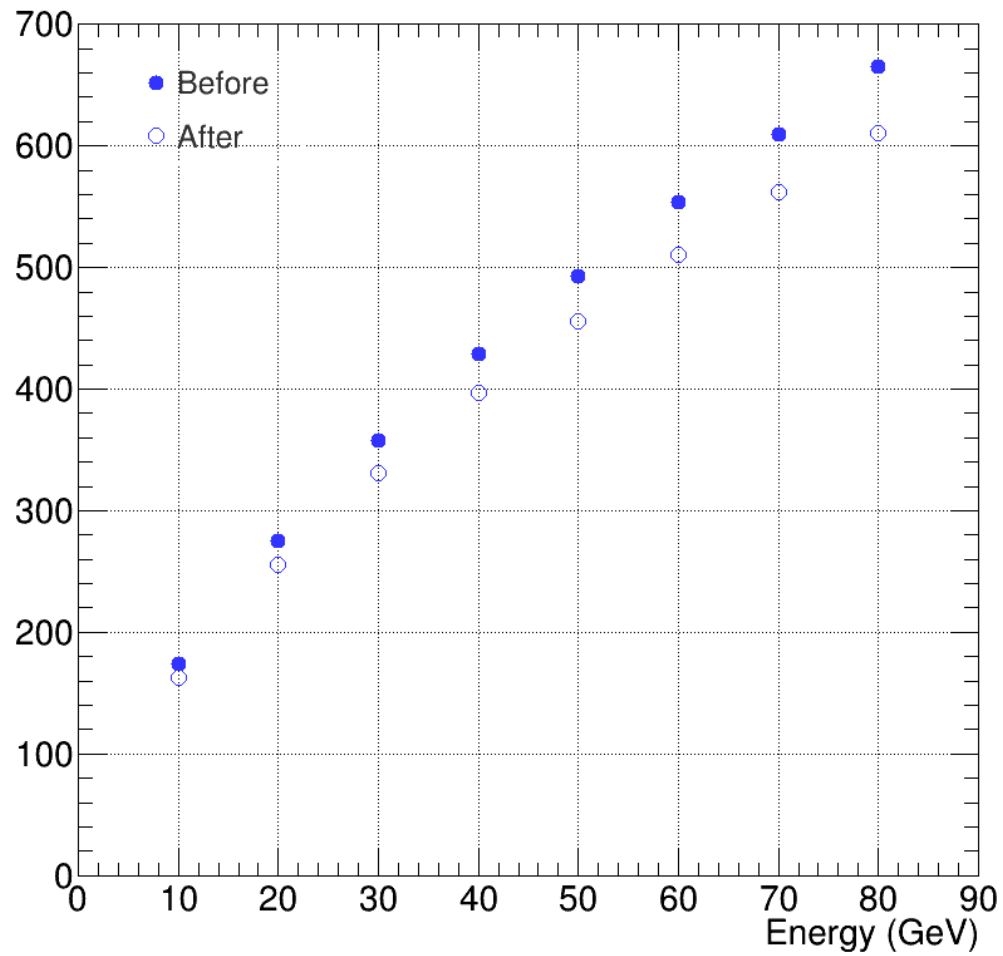


Simulation

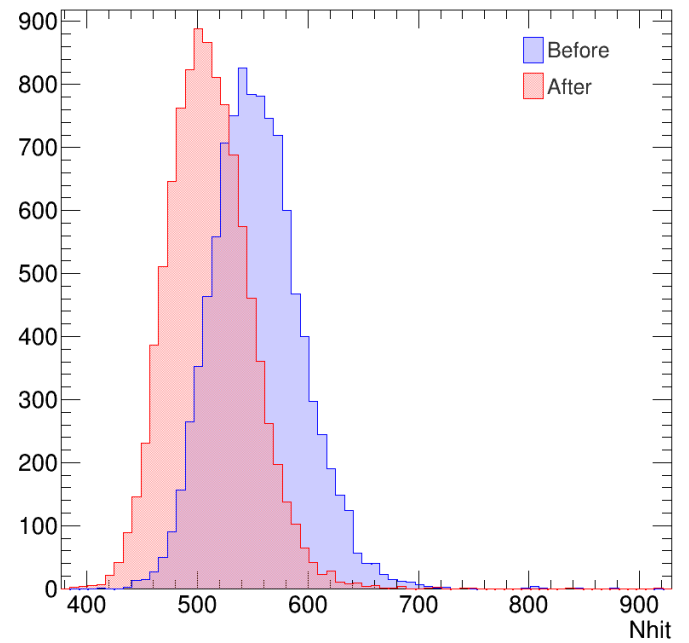
20 e⁻, FTF_BIC



N_{hit} e⁻



60 e⁻, FTF_BIC

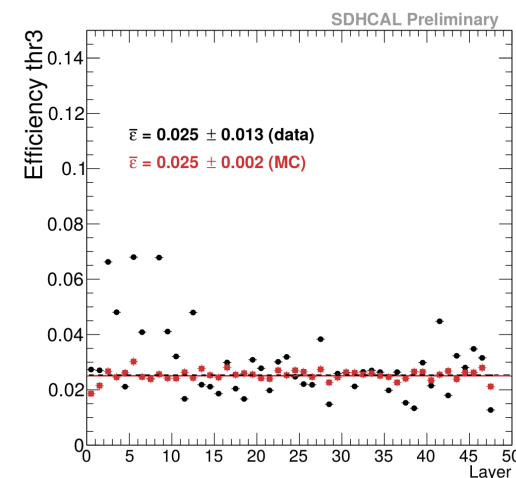
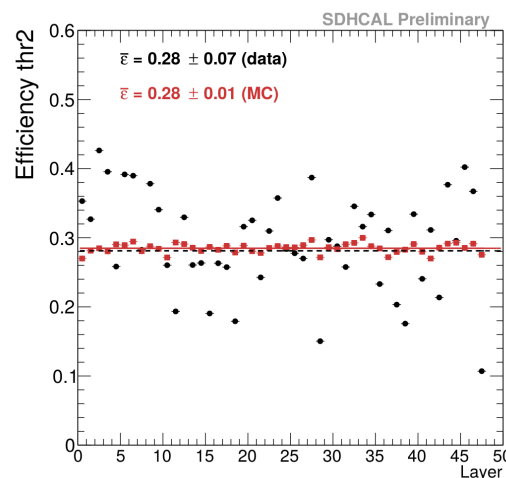
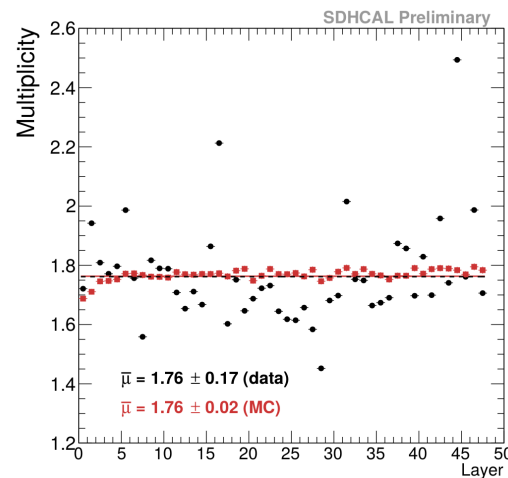
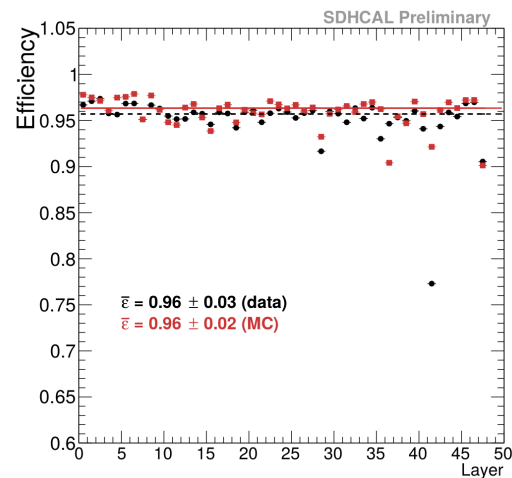


Digitizer

- New parametrization of the digitizer is needed due to simulation changes

- Current digitizer

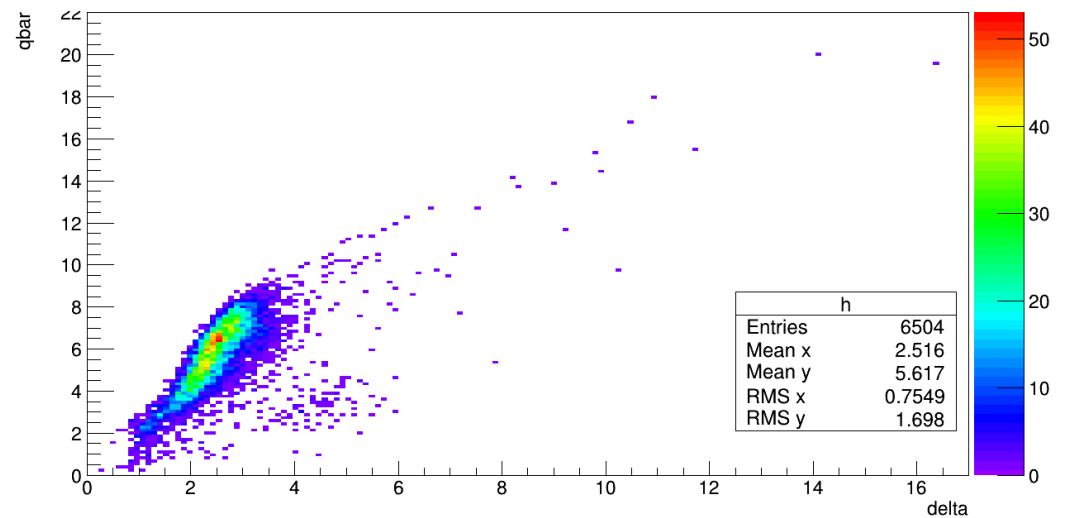
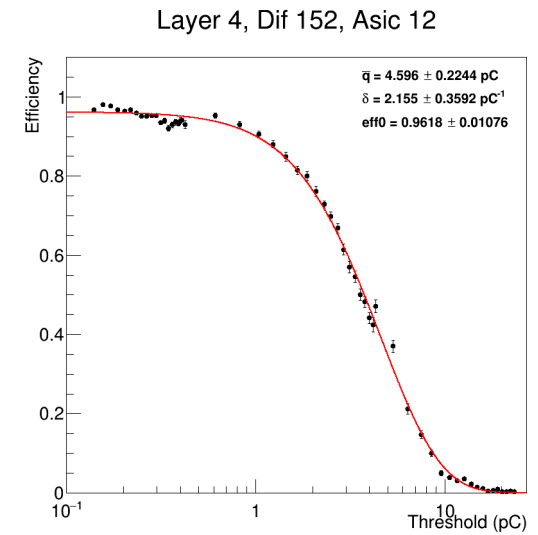
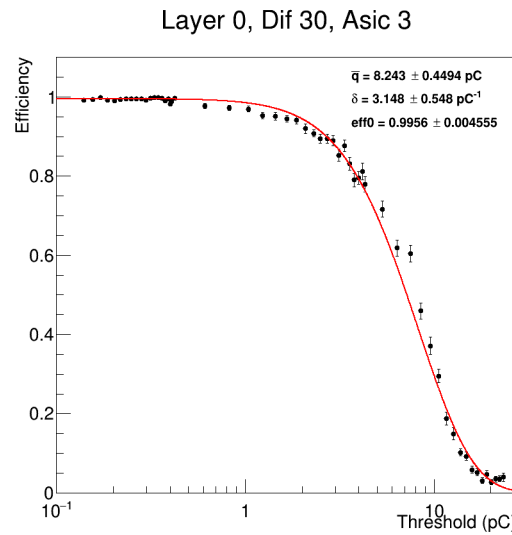
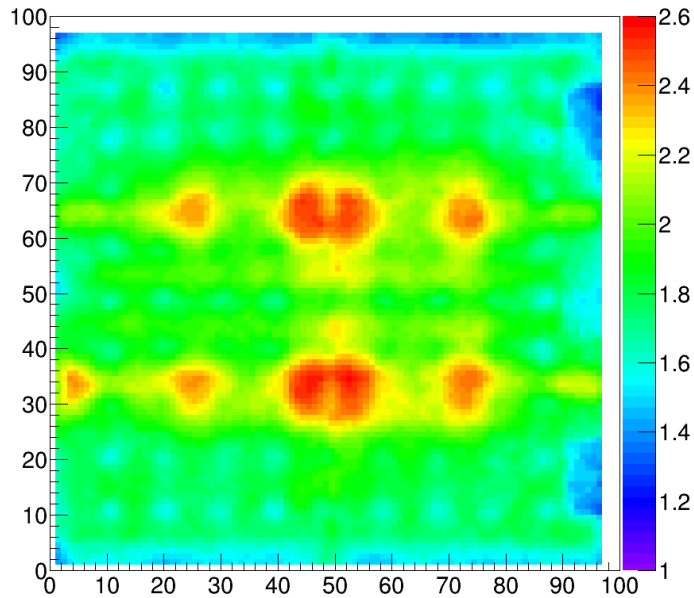
- Induced charge : $\frac{1}{\Gamma\left(\frac{\bar{q}}{\delta}\right)\delta^{\frac{\bar{q}}{\delta}}} \times q^{\frac{\bar{q}}{\delta}-1} e^{-\frac{q}{\delta}}$
- Charge spreading : $A_1 \times e^{-\frac{1}{2}\left(\frac{r}{\sigma_1}\right)^2} + A_2 \times e^{-\frac{1}{2}\left(\frac{r}{\sigma_2}\right)^2}$



- Average multiplicity and efficiencies are well reproduced, but not the fluctuations

Digitizer

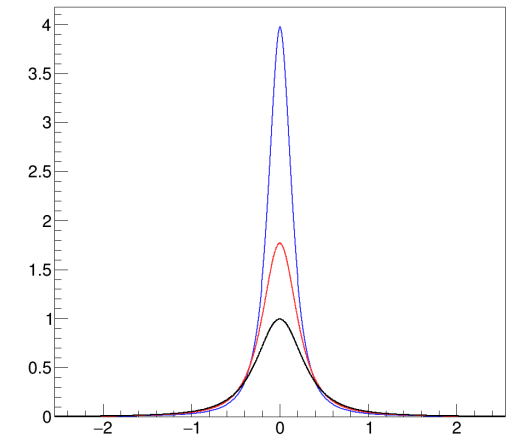
- October 2015 beam test
 - Threshold scan for all layers (except 1 and 34 which were off during the scan)
 - Enough statistics to study efficiencies and multiplicity **per ASIC**



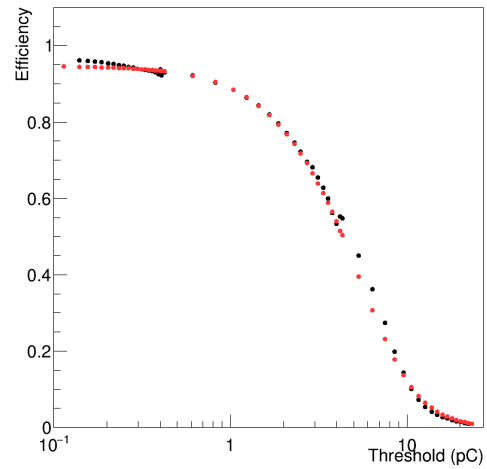
Digitizer

$$A \times \frac{d}{(r^2 + d^2)^{3/2}}$$

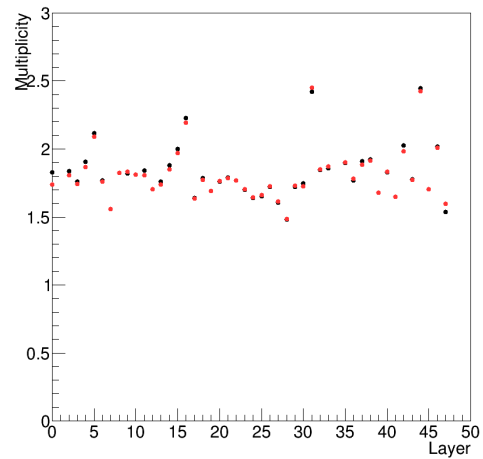
- New charge spreading distribution
 - 1 parameter instead of 4 : easier to tune
- 1 different set of parameters (\bar{q} , δ , d) per ASIC



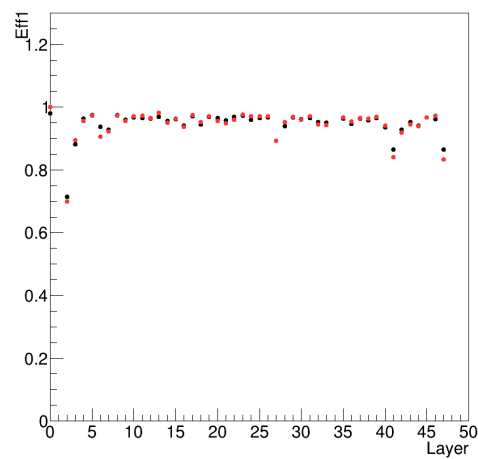
Layer -1, Dif -1, Asic -1



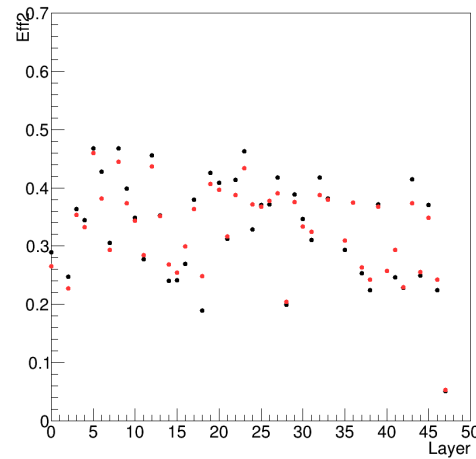
Multiplicity



Eff1



Eff2



Eff3

